

AMAT CMP TUNGSTEN AND OXIDE SLURRY CLEAN

OBJECTIVE:

TO ELIMINATE THE PROBLEMS ASSOCIATED WITH USING SCOTCH-BRITE™*
AND CERAMIC SCRAPPERS TO REMOVE TUNGSTEN AND OXIDE SLURRY FROM
CMP EQUIPMENT

PROBLEM:

- Using Scotch-Brite™ and/or ceramic scrappers to clean CMP tools
- Drying CMP pedestal with non-absorbent fab polyester wipes

RISK:

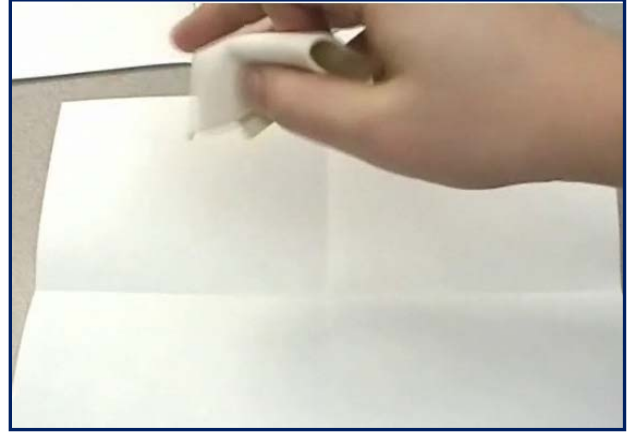
- RISK of Scotch-Brite™ residuals left inside CMP tool causing scratches on processed wafers
- Difficult to remove slurry built-up on Lexan panels without scratching panel
- Difficult to glue down new polishing pad onto wet surface

SOLUTION:

- **Diamond ScrubPAD** – Eliminates the use of Scotch-Brite™ and/or ceramic scrappers to remove slurry build up from CMP equipment
- **ScrubCLEAN® Sponge** – Effectively cleans Lexan panels without scratching surface
- **UltraSOLV® Sponge** – Effectively dries CMP pedestal



Scotch-Brite™* Residual



Diamond ScrubPAD Residual



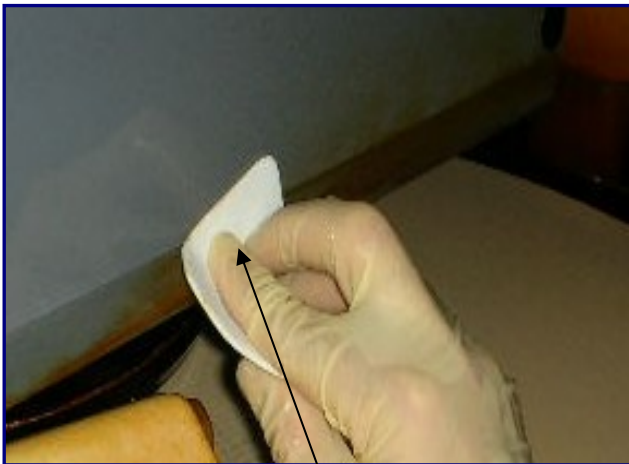
Why risk the dangers of using Scotch-Brite™?

TUNGSTEN SLURRY CLEAN: Diamond Grit ScrubPAD

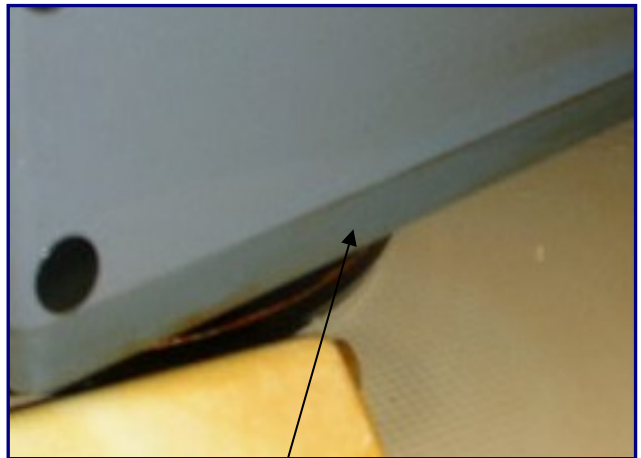


Diamond ScrubPAD

Scotch-Brite™*



**Diamond ScrubPAD Gently
Removing Slurry Build-Up**



Clean CMP Part

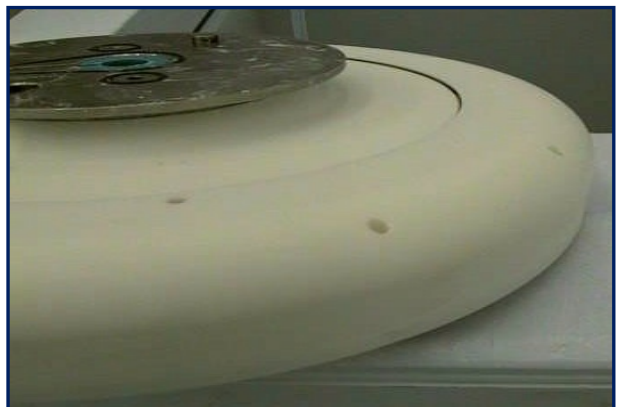
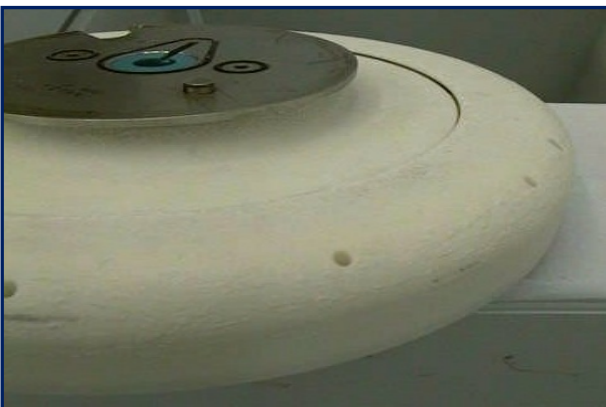
OXIDE SLURRY CLEAN: Diamond Grit ScrubPAD



BEFORE

AFTER

CMP POLISHING HEAD CLEAN: Diamond Grit ScrubPAD



BEFORE

AFTER

LEXAN PANEL CLEAN: FS206 ScrubCLEAN® Sponge



CMP Lexan Panel Coated With Slurry



**ScrubCLEAN® Gently
Removing CMP Slurry**



Clean Lexan Panel